Isolation Voltage	V_{iso}	5000	Vrms
Operating Temperature	T_{opr}	-40~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-40~125	
Soldering Temperature	T_{sol}	260	
Peak pulse voltage (T_j=25 ; non-repetitive,off-state)	V_{pp}	3	kV

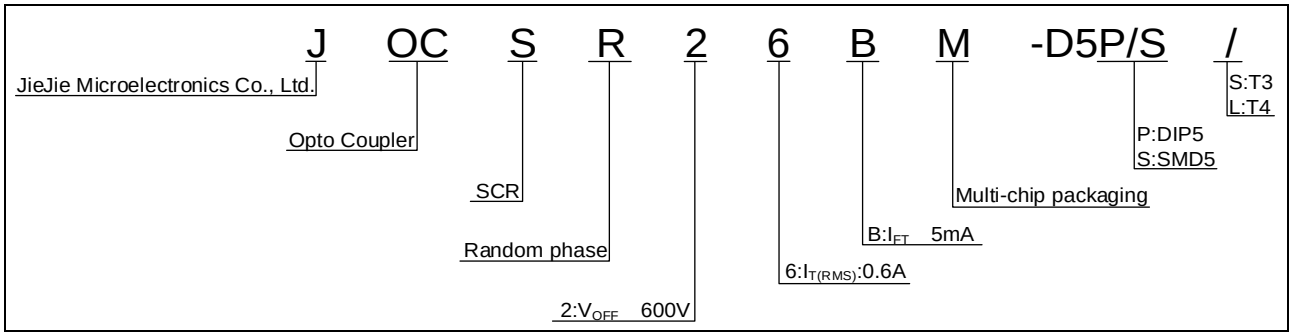
NOTE1 100μs pulse, 100Hz frequency

NOTE2 AC for 1minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

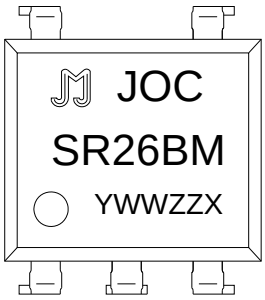
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
Output	Peak Off-state Current, Either Direction	I_{DRM}	V_{DRM} / V_{RRM} =600V, I_F=0	-	-	5	μA
		I_{RRM}		-	-	5	
	Peak On-state Voltage, Either Direction	V_{TM}	I_{TM}= I_{TM} Rated	-	-	1.7	V
	Critical Rate of Rise of Off-state voltage	dV/dt	V_D=400V, Gate Open I_F=0, T_j=125	1000	-	-	V/μs
	Critical Rate of Rise of Commutating Voltage	(dV/dt)c	(dI/dt)c =1.5A/ms, T_j=125	10	-	-	V/μs
Transfer Characteristics	LED Trigger Current	I_{FT}	Terminal Voltage=6V R_L=100Ω	-	-	5	mA
	Holding Current	I_H	V_D=6V	-	-	25	mA
	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	Ω
	Response Time	t_{on}	V_D=6V, R_L=100Ω, I_F=20mA	-	20	100	μs

ORDERING INFORMATION



Packing Quantity	
Option	**Quantity**
DIP	60 Units/Tube
SMD	1200 Units/Reel

MARKING



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

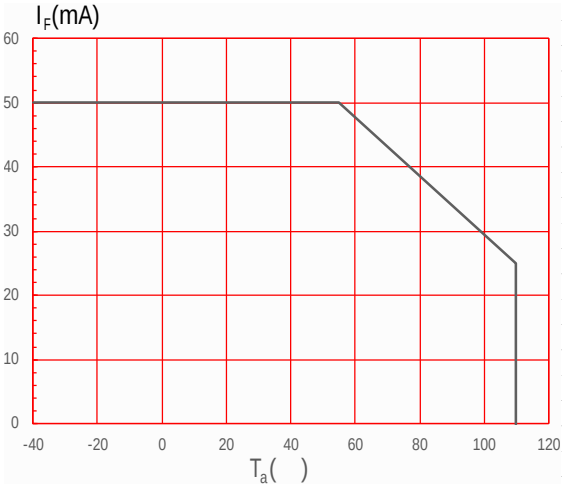


FIG.2: On-state Terminal Current vs. Ambient Temperature

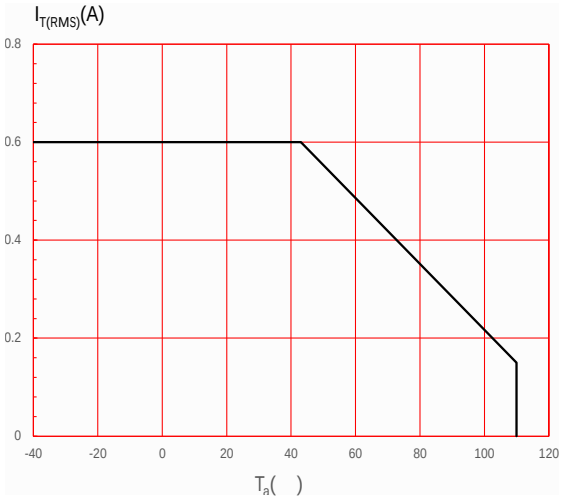


FIG.3: Forward Current vs. Forward Voltage

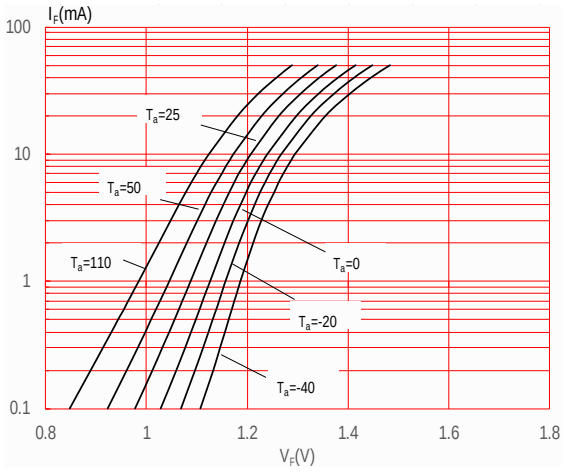


FIG.4: Forward Voltage vs. Ambient Temperature

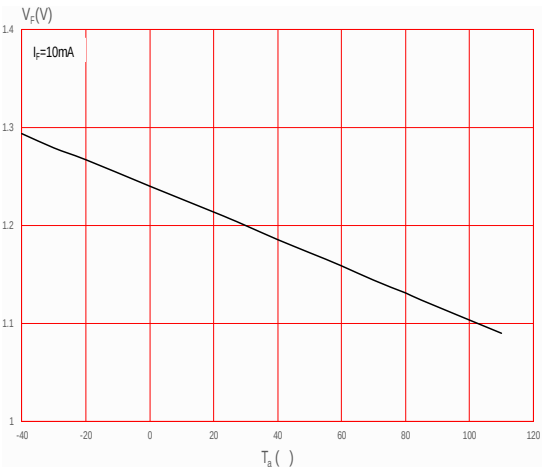


FIG.5: Off-state Terminal Current vs Off-state Terminal Voltage

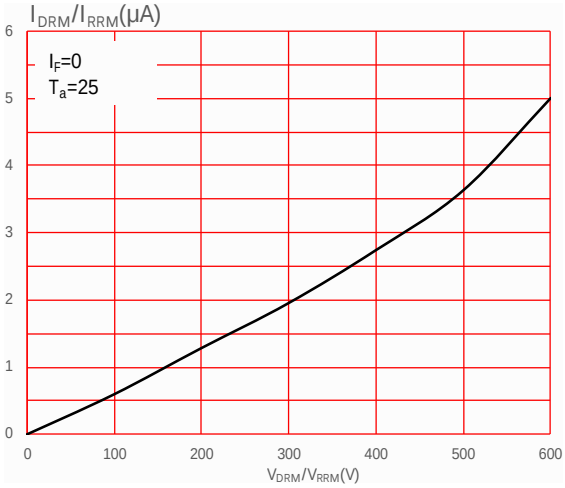


FIG.6: Normalized Trigger Current vs. Ambient Temperature

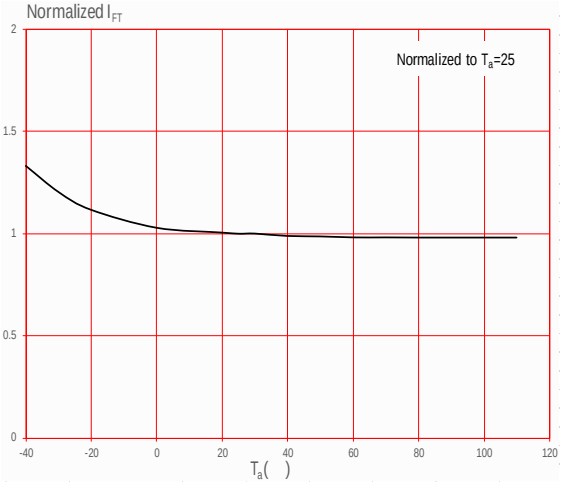


FIG.7: On-state characteristics

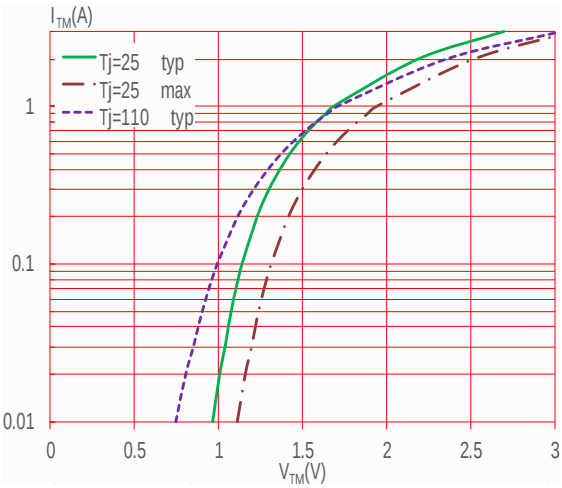


FIG.8: Normalized Holding Current vs. Ambient Temperature

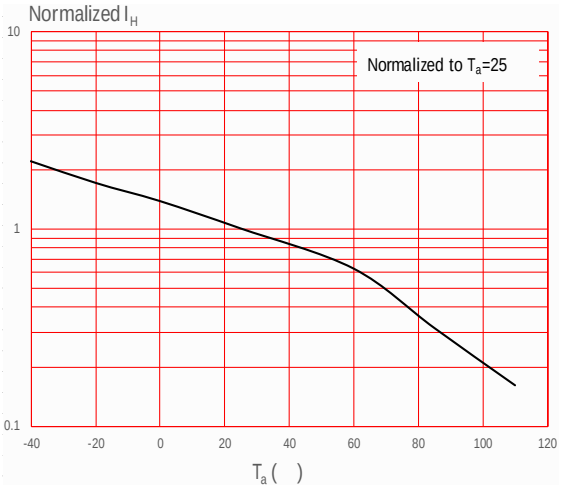
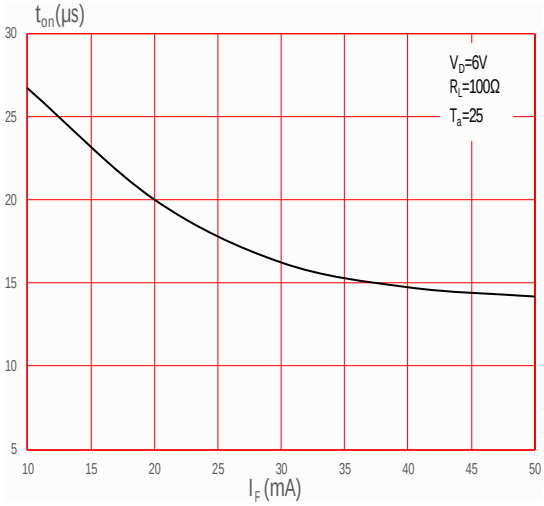


FIG.9: Turn On Time vs. Forward Current

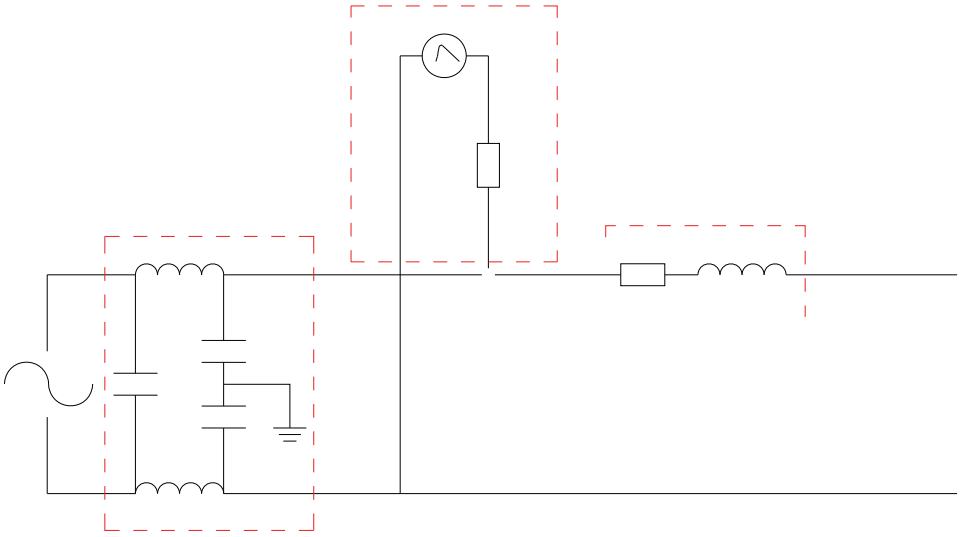


TEST CIRCUITS

FIG.10: Test Circuits of Turn On Time

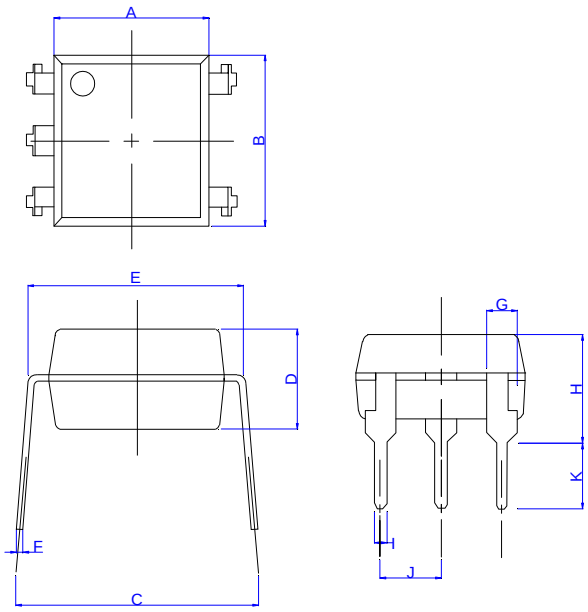
FIG.11: Waveforms of Turn On Time

FIG.12: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



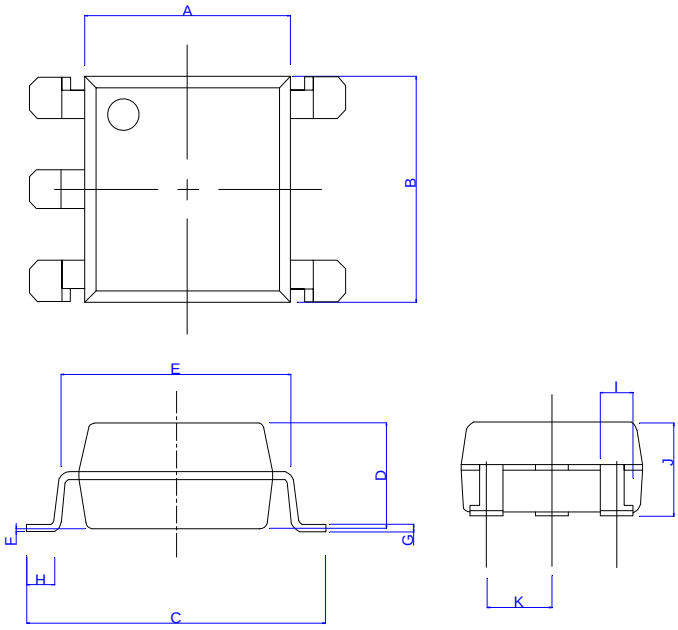
Package Dimension (Unit: mm)

Standard DIP Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	1.15		1.35	0.045		0.053
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

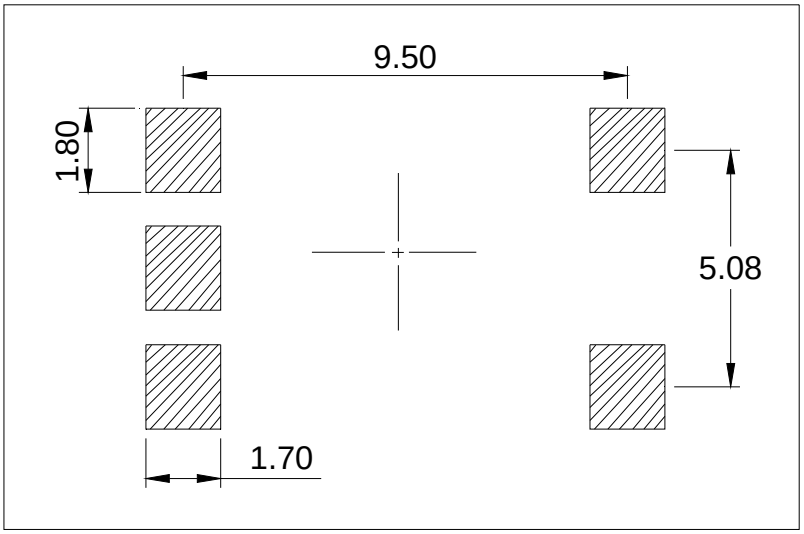
Option SMD Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	6.92		7.32	0.272		0.288
C	9.50		10.50	0.375		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

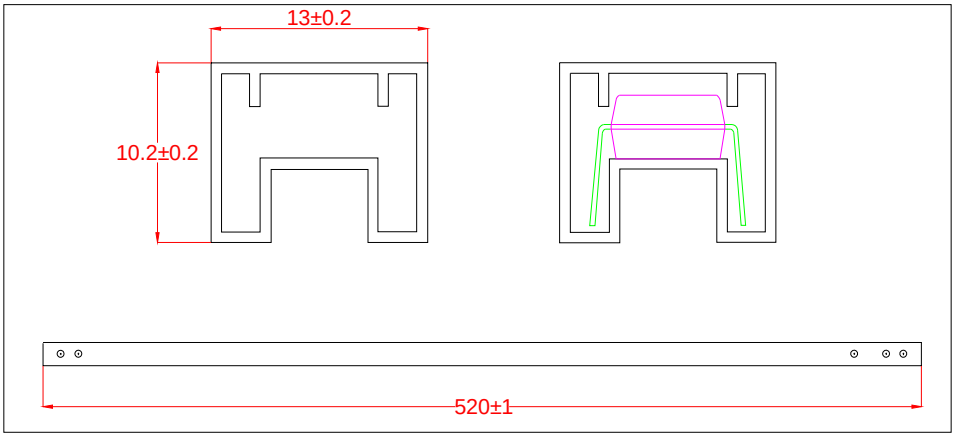
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SMD



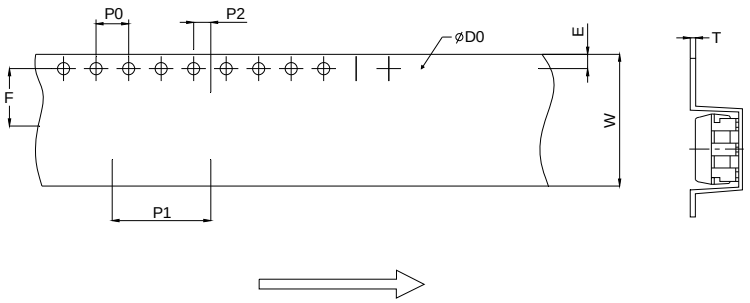
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



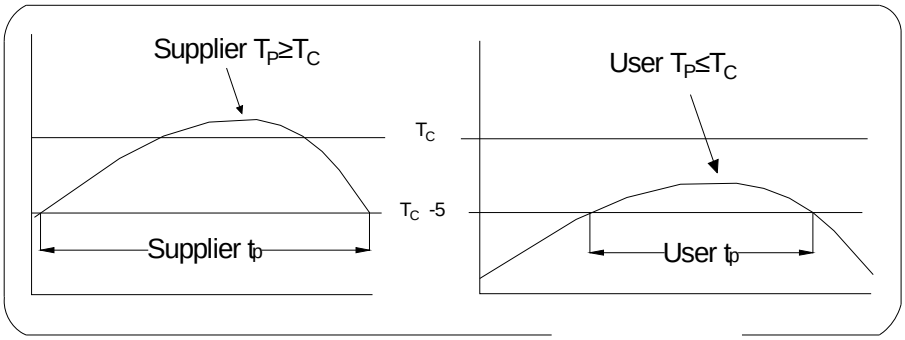
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

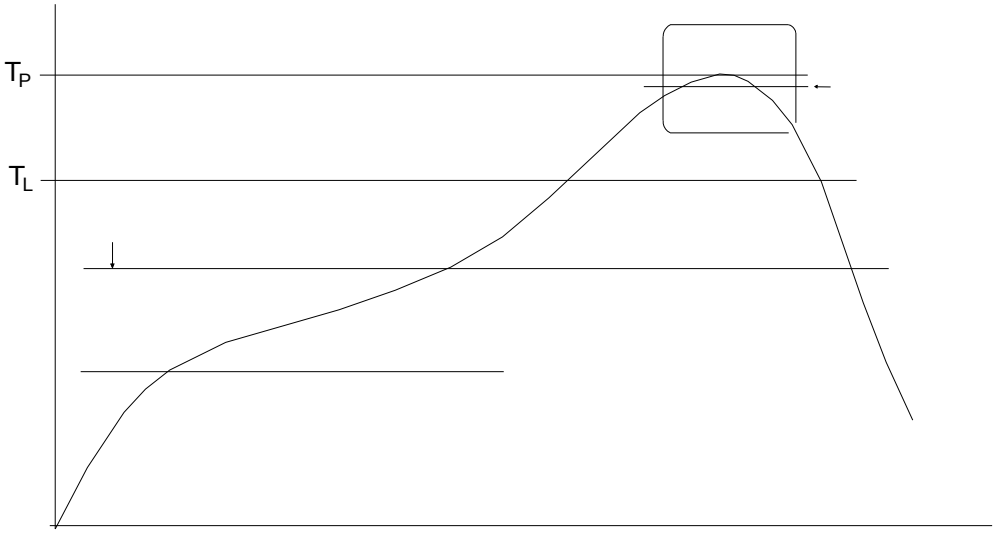
Option S/L



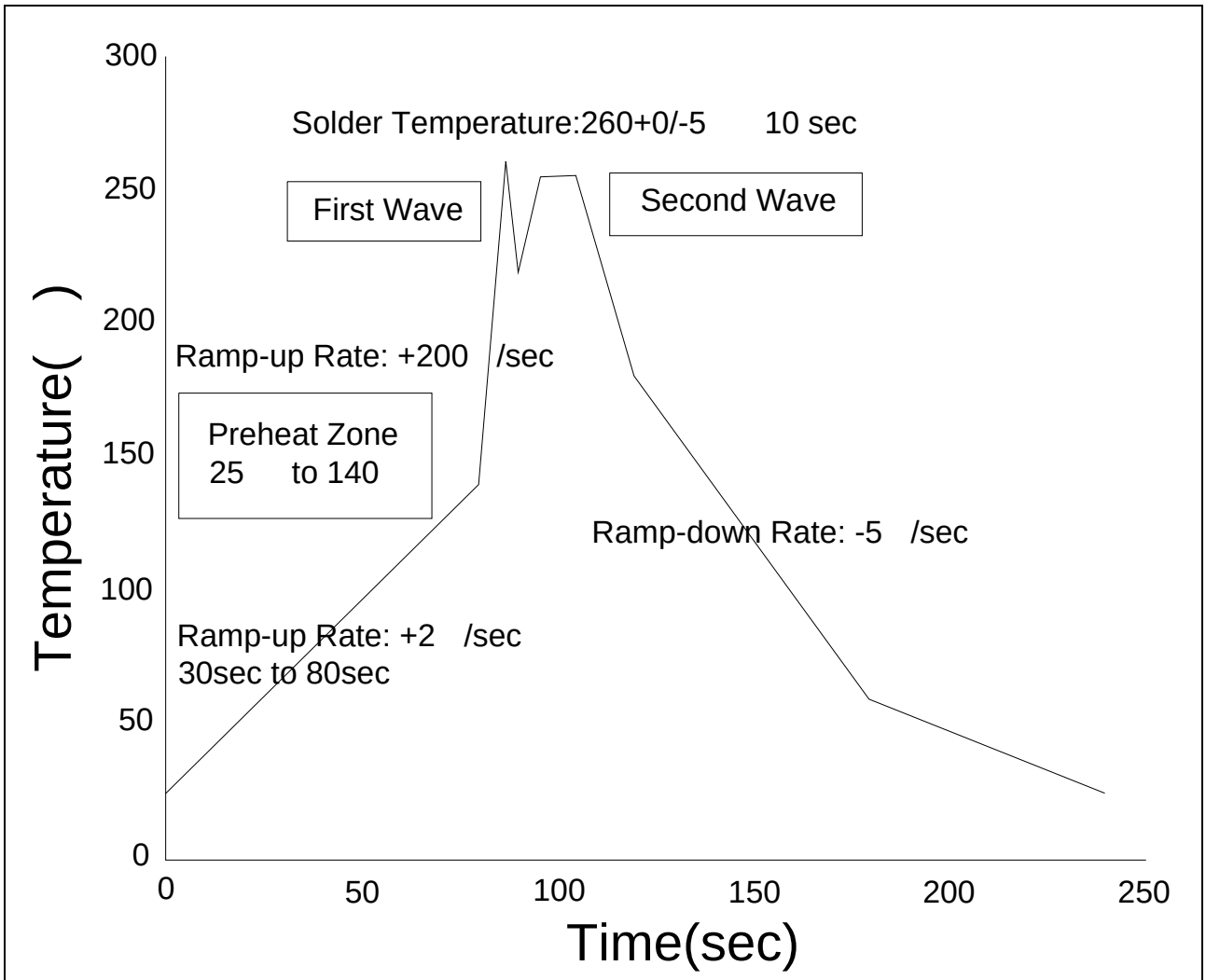
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

REFLOW INFORMATION





WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1